

## 1200V N-Channel Silicon Carbide Power MOSFET

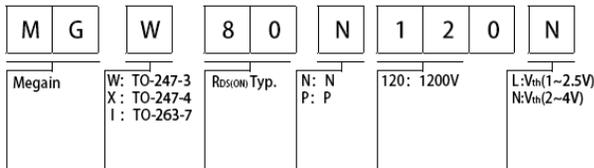
### Product Summary

- $V_{DS}$  1200V
- $I_D$  35A
- $R_{DS(ON)}$  (at  $V_{GS} = 20V$ ) 71m $\Omega$  (Max: 92m $\Omega$ )
- $R_{DS(ON)}$  (at  $V_{GS} = 18V$ ) 80m $\Omega$  (Max: 104m $\Omega$ )
- $R_{DS(ON)}$  (at  $V_{GS} = 15V$ ) 100m $\Omega$  (Max: 130m $\Omega$ )

### Applications

- PV string inverters
- Solar power optimizer
- Switch mode power supplies
- Online UPS/Industrial UPS
- High Voltage DC/DC Converters

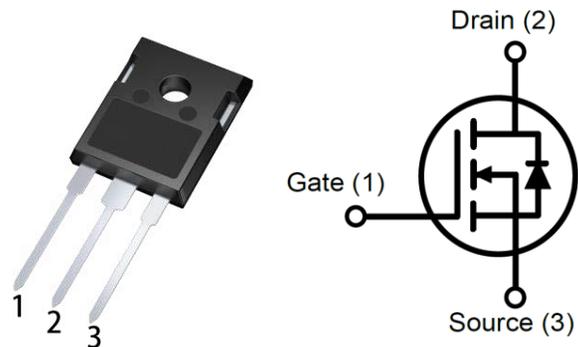
### Naming Convention



### Features

- High speed switching
- Very low switching losses
- High blocking voltage with low on-resistance
- Temperature independent turn-off switching losses
- Halogen free, RoHS compliant

### Package & Pin Configuration



### Ordering Information

Order code	Package	Form	Quantity (PCS)	Marking
MGW80N120N	TO-247-3	Tube	30 / Tube	MGW80N120N

### Absolute Maximum Ratings

$T_c=25^\circ\text{C}$  Unless Otherwise Noted.

Symbol	Parameter	Test Conditions	Value	Units
$V_{DS}$	Drain-Source Voltage	$V_{GS} = 0\text{ V}, I_D = 100\mu\text{A}$	1200	V
$I_D^{(1)}$	Drain Current – Continuous	$V_{GS} = 18\text{ V}, T_c = 25^\circ\text{C}$	35	A
$I_{DM}^{(2)}$	Drain Current – Pulsed		106	A
$P_D^{(1)}$	Total Power Dissipation	$T_c = 25^\circ\text{C}$	175	W
$V_{GS}$	Recommend Gate Source Voltage		-5/+18	V
	Maximum Gate Source Voltage		-10/+25	
$T_{STG}$	Storage Temperature Range		-55 to 175	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range		-55 to 175	$^\circ\text{C}$
$T_L$	Soldering Temperature		260	$^\circ\text{C}$

(1)  $I_D$  and  $P_D$  are limited by package.

(2) Pulse width is limited by safe operating area.

■ **Thermal Characteristics**

Symbol	Parameter	Max	Typ	Max	Units
$R_{\theta JC}$	Thermal Resistance Junction to Case	-	0.86	-	$^{\circ}\text{C}/\text{W}$

■ **Electrical Characteristics**

$T_J=25^{\circ}\text{C}$  Unless Otherwise Noted.

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
<b>Static</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 100\mu A$	1200	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 1200V, V_{GS} = 0V$	-	1	100	$\mu A$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS} = 18V$	-	1	100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 10mA$	1.8	2.7	3.6	V
$R_{DS(ON)}$	Drain-Source On-state Resistance	$V_{GS} = 18V, I_D = 15A$	-	80	104	m $\Omega$
		$V_{GS} = 15V, I_D = 15A$	-	100	130	
<b>Dynamic</b>						
$C_{iss}$	Input Capacitance	$V_{GS} = 0V, V_{DS} = 800V,$ $f = 1MHz,$ $V_{AC} = 25mV$	-	659	-	pF
$C_{oss}$	Output Capacitance		-	45	-	
$C_{rss}$	Reverse Transfer Capacitance		-	5	-	
$E_{oss}$	$C_{oss}$ Stored Energy				25	
$Q_g$	Total Gate Charge	$V_{DS} = 800V,$ $V_{GS} = -5/+18V,$ $I_D = 15A$	-	54	-	nC
$Q_{gs}$	Gate-Source Charge		-	9.5	-	
$Q_{gd}$	Gate-Drain Charge		-	30.5	-	
$R_{G(int)}$	Internal Gate Resistance	$f = 1MHz, V_{AC} = 25mV$	-	1	-	$\Omega$
$t_{d(ON)}$	Turn-on Delay Time	$V_{DS} = 800V,$ $V_{GS} = -5/+18V,$ $R_G = 2.5\Omega,$ $I_D = 15A$	-	11	-	nS
$t_r$	Turn-on Rise Time		-	12	-	
$t_{d(OFF)}$	Turn-off Delay Time		-	23	-	
$t_f$	Turn-off Fall Time		-	7.5	-	
$E_{ON}$	Turn-on Switching Energy	$V_{DS} = 800V,$ $V_{GS} = -5/+18V,$ $R_G = 2.5\Omega, I_D = 15A$	-	121	-	$\mu J$
$E_{OFF}$	Turn-off Switching Energy		-	24	-	$\mu J$
<b>Body Diode Characteristics</b>						
$I_S$	Continuous Source Current		-	-	35	A
$V_{SD}$	Diode Forward Voltage	$V_{GS} = 0V, I_S = 15A$	-	4.3	-	V
$t_{rr}$	Reverse Recovery Time	$I_S = 15A, V_{DS} = 800V$ $V_{GS} = -5V$ $di/dt = 1000A/\mu s$	-	21.5	-	nS
$Q_{rr}$	Reverse Recovery Charge		-	113	-	nC
$I_{rrm}$	Peak Reverse Recovery Current		-	9	-	A

■ Typical Characteristics

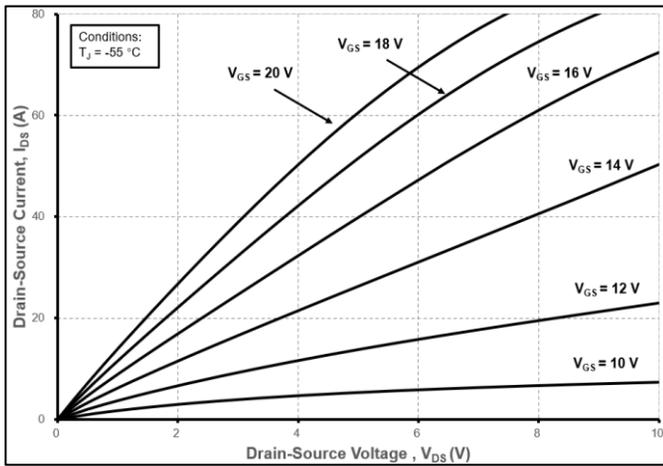


Fig 1. Typical Output Characteristics at  $T_J = -55^\circ\text{C}$

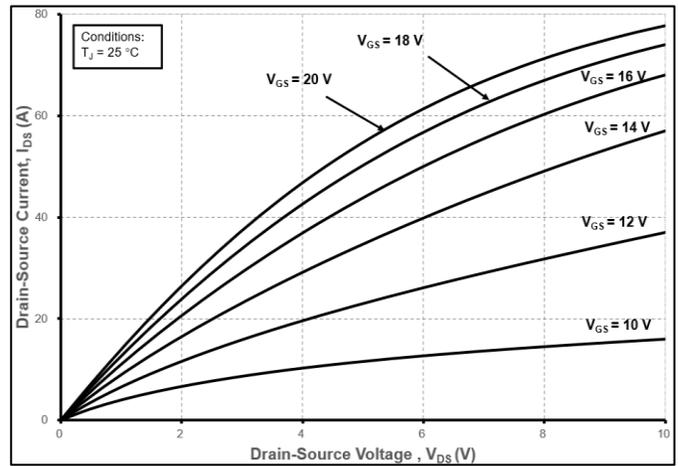


Fig 2. Typical Output Characteristics at  $T_J = 25^\circ\text{C}$

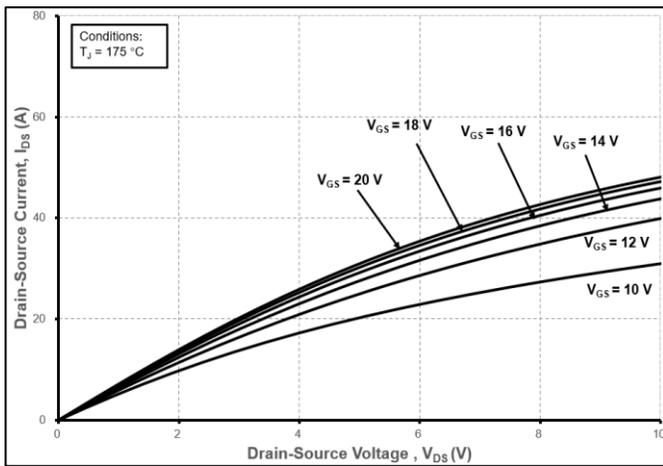


Fig 3. Typical Output Characteristics at  $T_J = 175^\circ\text{C}$

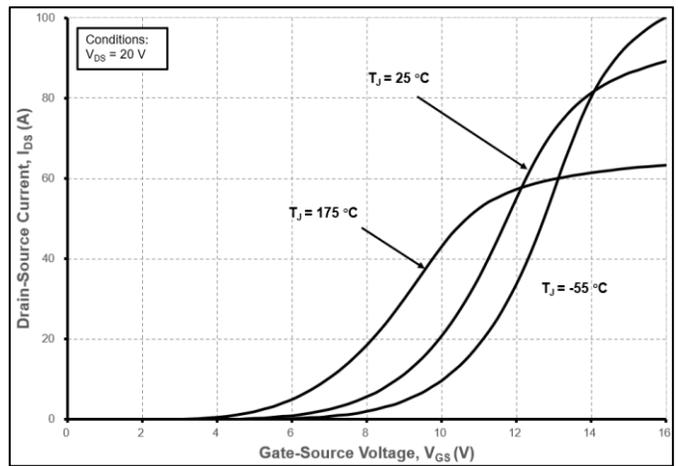


Fig 4. Typical Transfer Characteristics for Various Temperatures

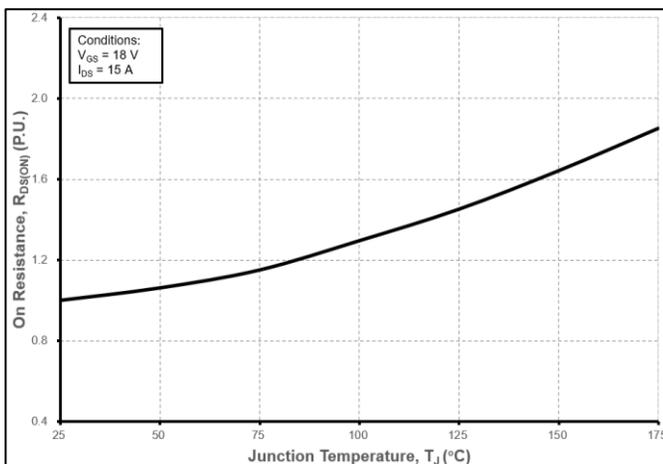


Fig 5. Normalized On-Resistance vs. Temperature

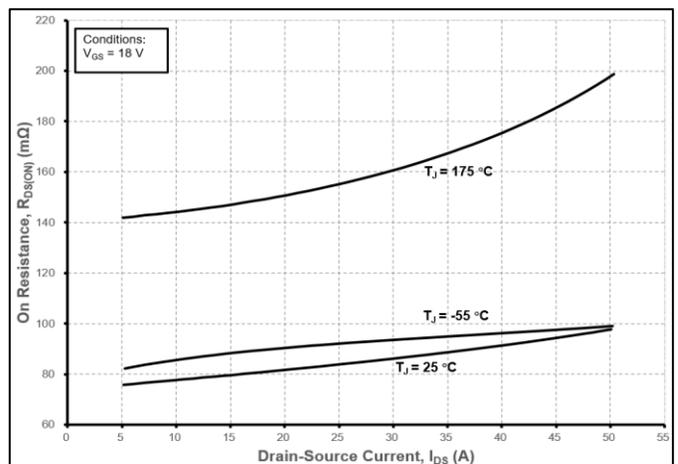


Fig 6. On-Resistance vs. Drain Current for Various Temperatures

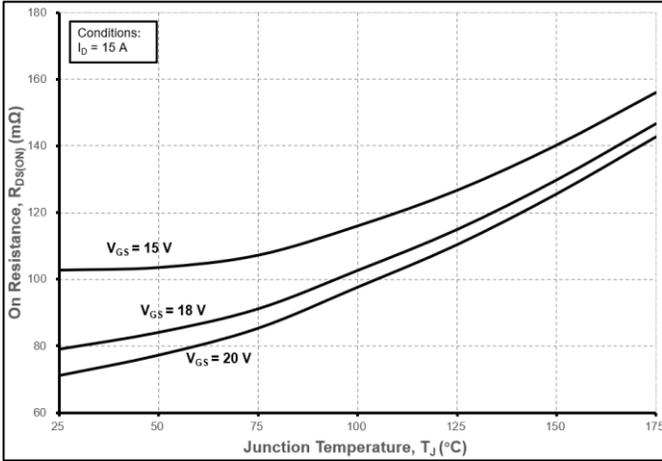


Fig 7. On-Resistance vs. Temperature for Various Gate Voltage

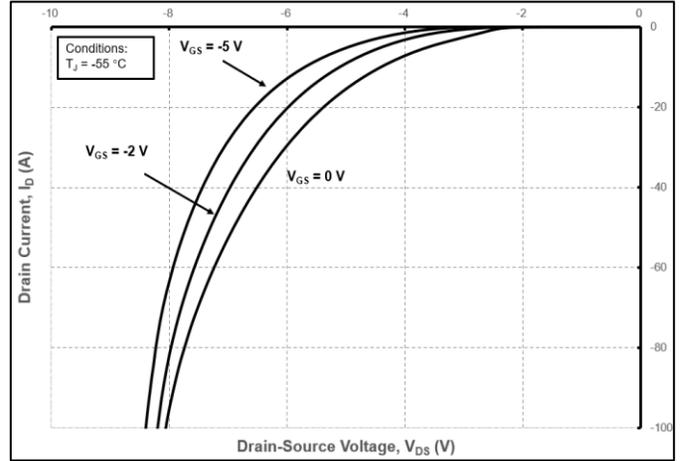


Fig 8. Typical Body Diode Characteristics at  $T_J = -55^\circ\text{C}$

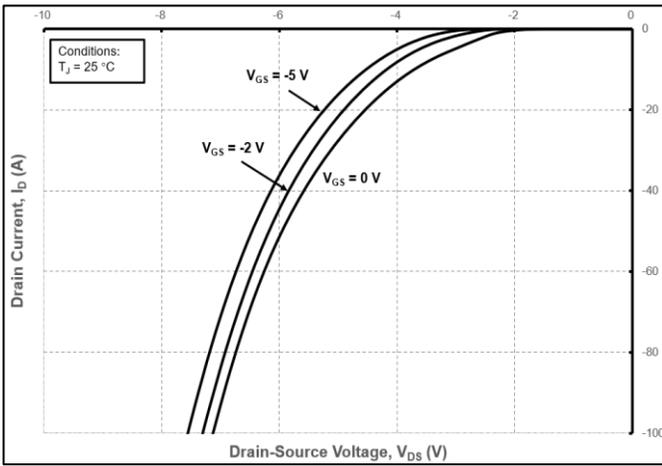


Fig 9. Typical Body Diode Characteristics at  $T_J = 25^\circ\text{C}$

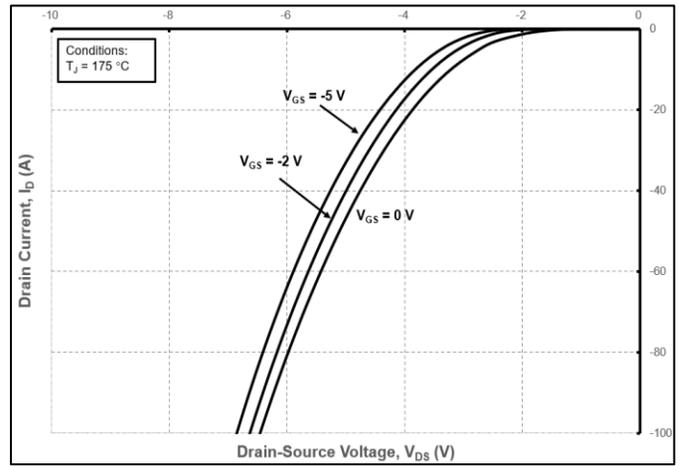


Fig 10. Typical Body Diode Characteristics at  $T_J = 175^\circ\text{C}$

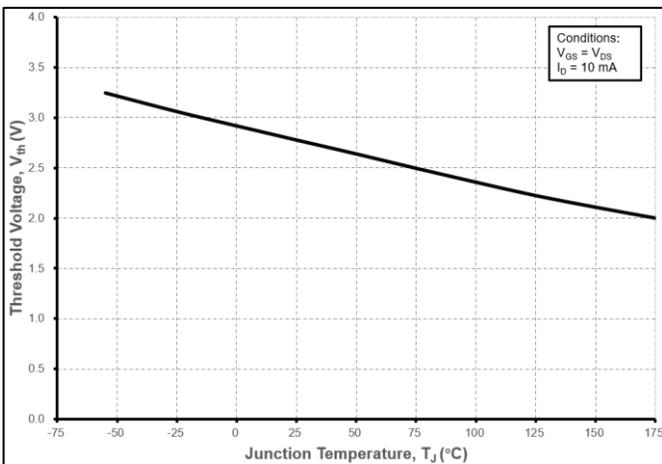


Fig 11. Typical Threshold Voltage vs. Temperature

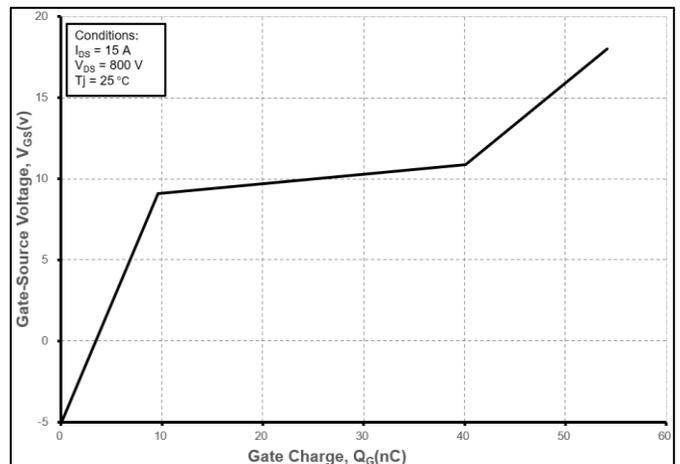


Fig 12. Gate Charge Characteristics

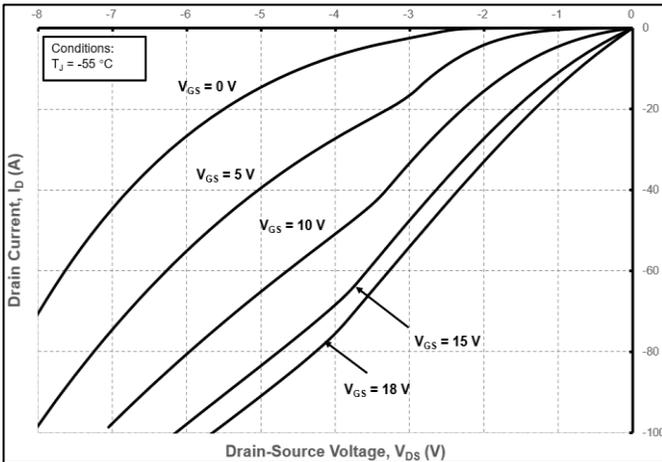


Fig 13. Typical 3rd Quadrant Characteristics at  $T_J = -55^\circ\text{C}$

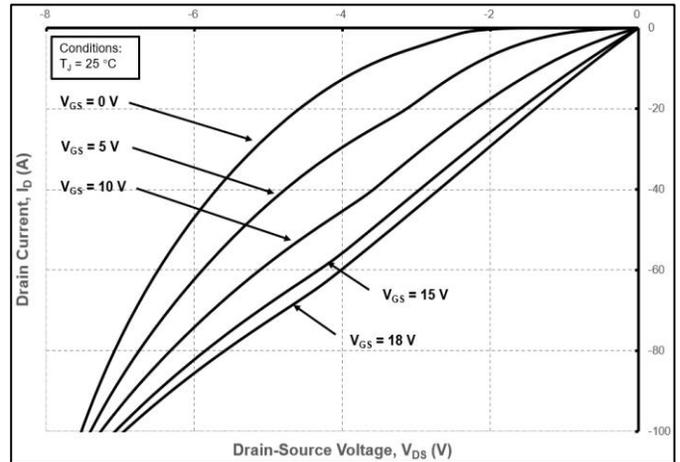


Fig 14. Typical 3rd Quadrant Characteristics at  $T_J = 25^\circ\text{C}$

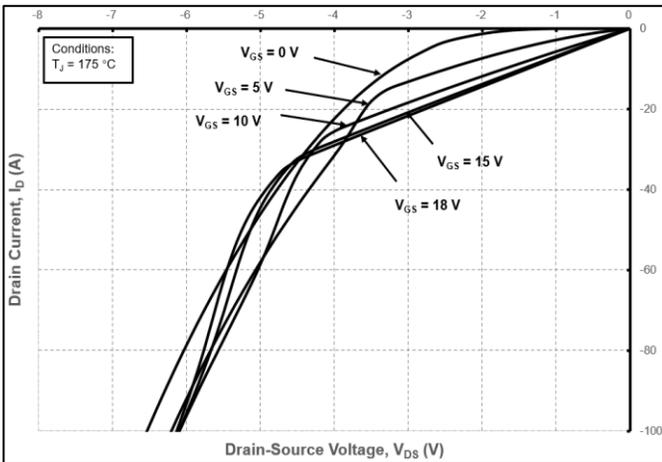


Fig 15. Typical 3rd Quadrant Characteristics at  $T_J = 175^\circ\text{C}$

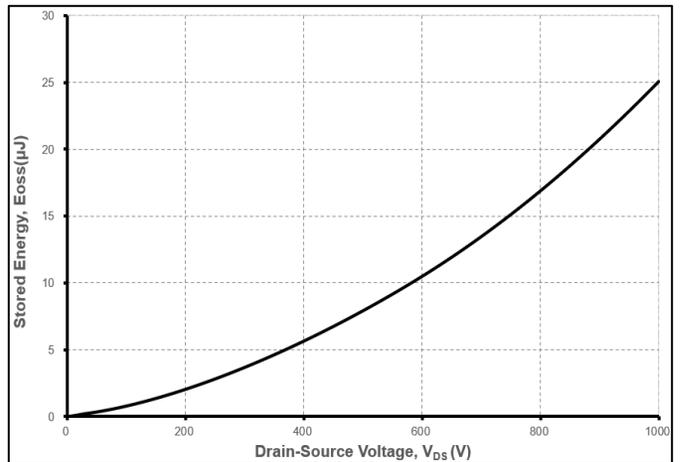


Fig 16. Output Capacitor Stored Energy

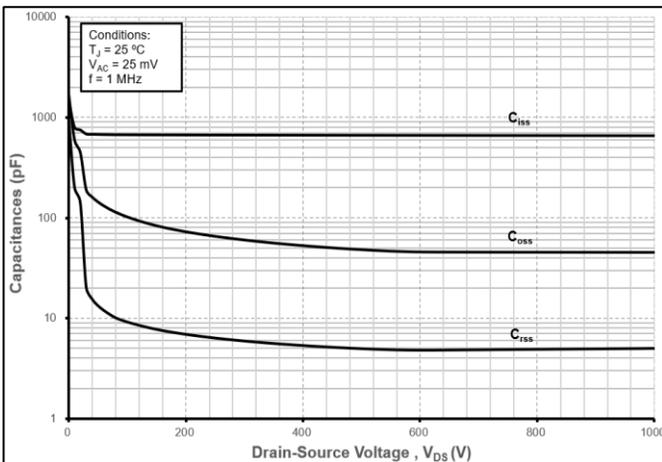


Fig 17. Capacitances vs. Drain-Source Voltage

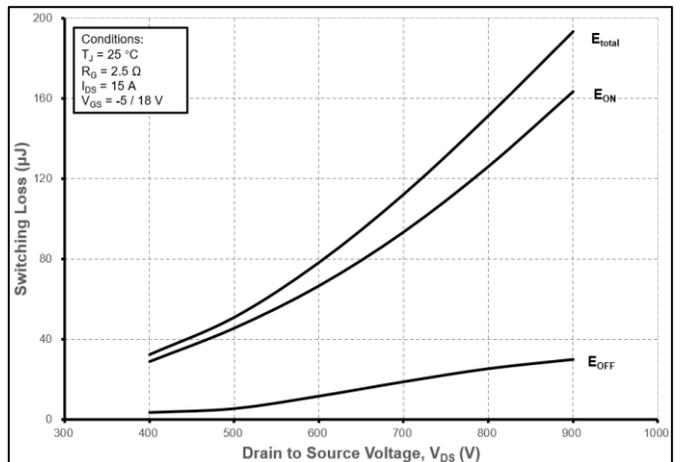


Fig 18. Clamped Inductive Switching Energy vs.  $V_{DS}$

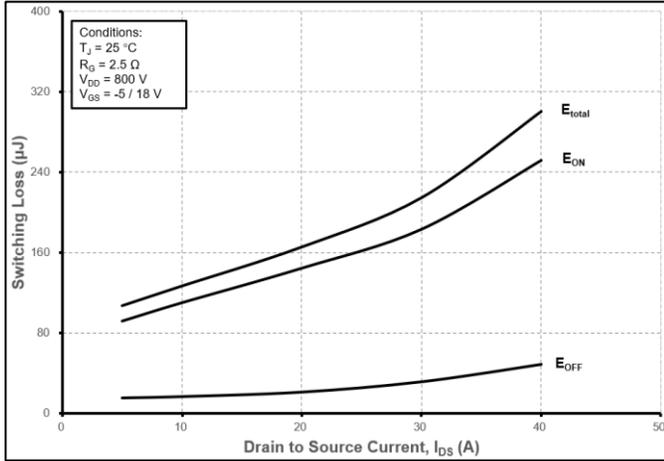


Fig 19. Clamped Inductive Switching Energy vs.  $I_{DS}$

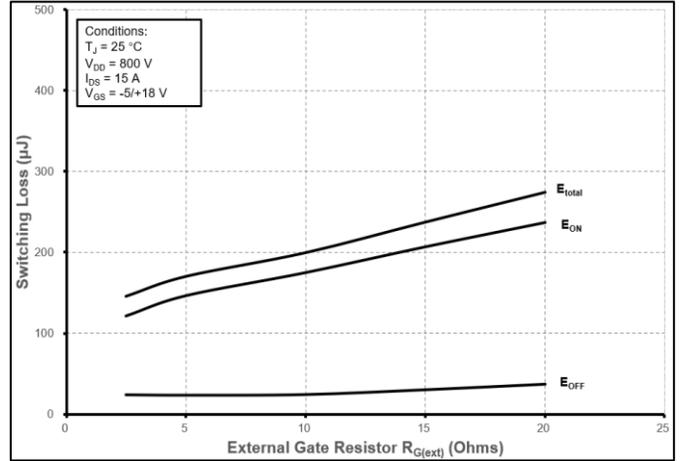


Fig 20. Clamped Inductive Switching Energy vs.  $R_{G(ext)}$

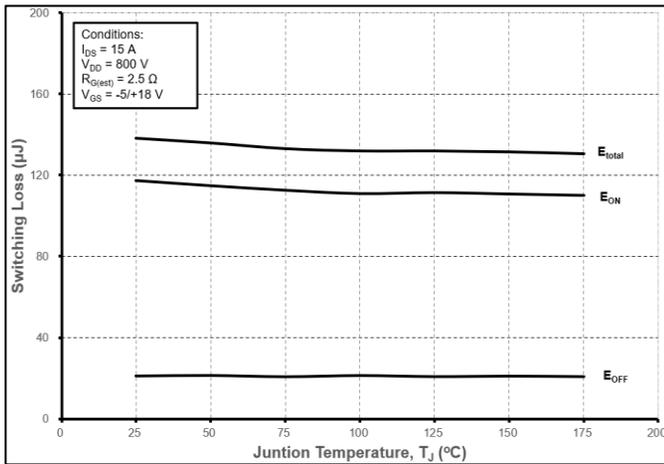


Fig 21. Clamped Inductive Switching Energy vs.  $T_J$

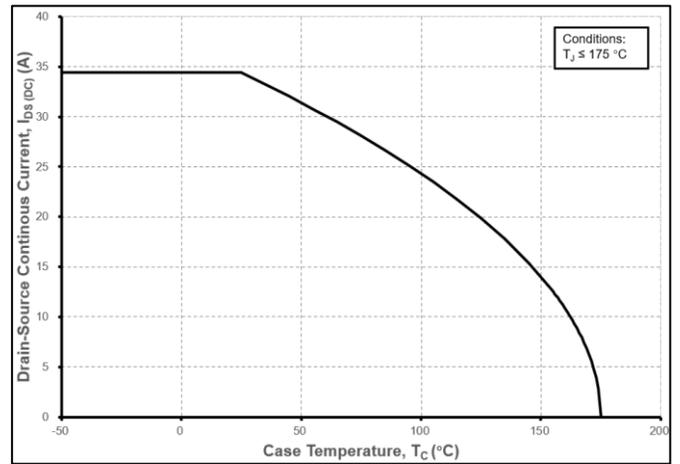


Fig 22. Continuous  $I_{DS}$  Current Derating Curve

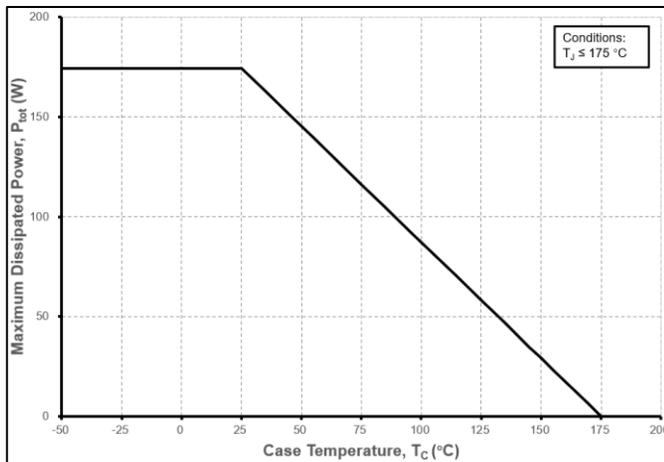


Fig 23. Power Dissipation Derating Curve

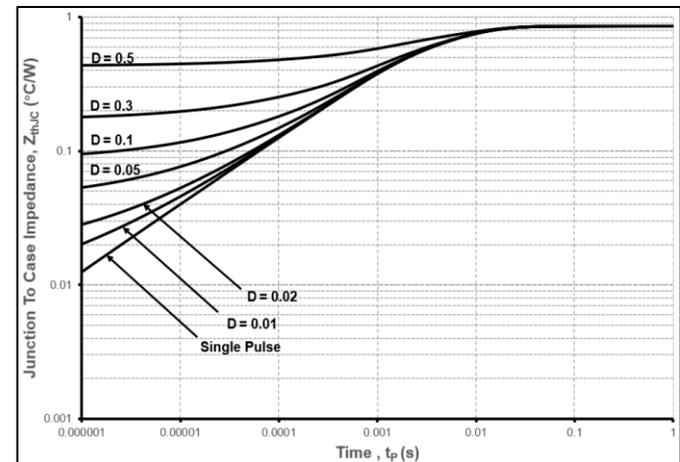


Fig 24. Typical Transient Thermal Impedance

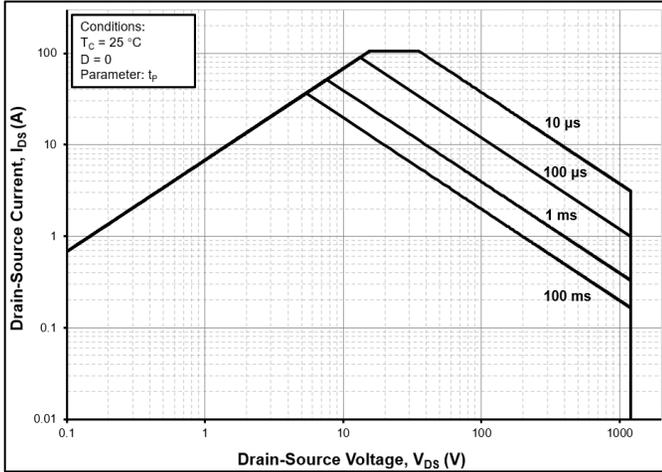
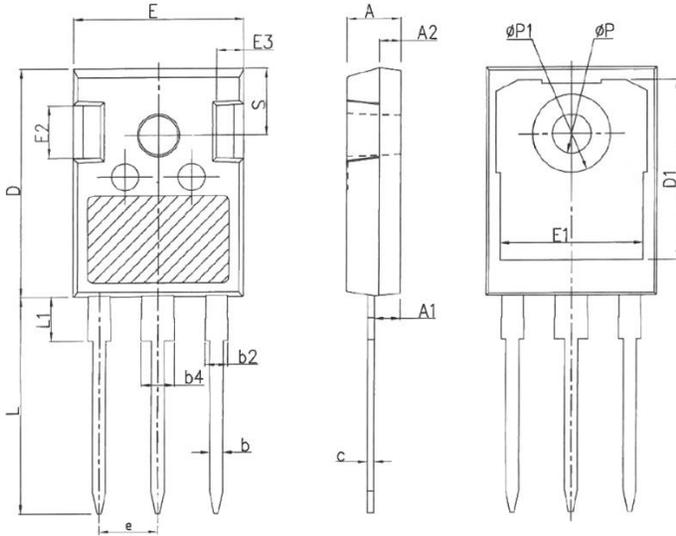


Fig 25. Safe Operating Area

■ Package size

Unit: mm。

TO-247-3:



SYMBOL	Unit: mm		
	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.21	2.41	2.59
A2	1.85	2.00	2.15
b	1.11	1.21	1.36
b2	1.91	2.01	2.21
b4	2.91	3.01	3.21
c	0.51	0.61	0.75
D	20.70	21.00	21.30
D1	16.25	16.55	16.85
E	15.50	15.80	16.10
E1	13.00	13.30	13.60
E2	4.80	5.00	5.20
E3	2.30	2.50	2.70
e	5.44 BSC		
L	19.62	19.92	20.22
L1	-	-	4.30
ΦP	3.40	3.60	3.80
ΦP1	-	-	7.30
S	6.15 BSC		